

# Electrostatic Doping Assisted Push-Pull Mach-Zehnder Modulator For Optical Interconnects

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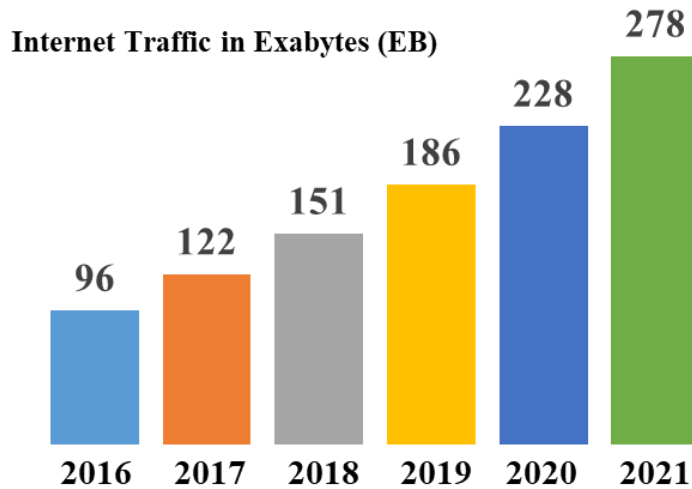
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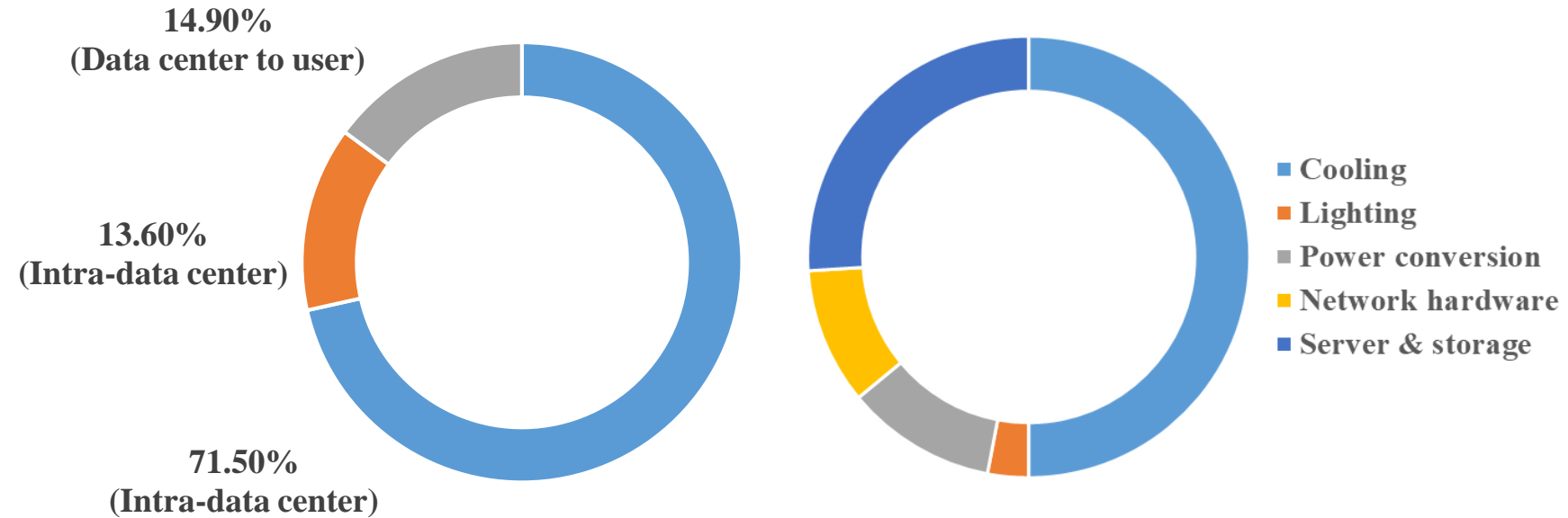


# Why Silicon Photonics?

Year Wise Demand of Internet Traffic



Power Consumption in Data Center



## Problems in Present Design

- Fixed bandwidth capability.
- High power consumption.
- Scaling limitation.

## Solution(s)

- Replacement of copper based interconnects by photonic interconnects.
- Integration of electronic and photonic circuits.



# Why Silicon Photonics?

## Advantages of Silicon

- Stable and well understood material.
- Mature fabrication technology.
- High optical confinement and refractive index.
- Optically transparent at  $1.3\ \mu\text{m}$  to  $1.5\ \mu\text{m}$ .
- Electro-refraction and electro-absorption: dual method for optical modulation.
- Offers electronic and optical integration.

## Requirements of Silicon Based Interconnects

- Power Requirement<sup>1</sup>: Inter-chip:  $\leq 100\ \text{fJ/bit}$ ; Intra-chip:  $\leq 50\text{-}200\ \text{fJ/bit}$ .
- Photodetectors integrated with transistors.
- Total time delay:  $180\text{-}270\ \text{ps}$ .
- Total power consumption:  $18\text{-}20\ \text{mW}$ .

1. D. Miller, Proc. IEEE, vol. 97, no. 7, pp. 1166-85, 2009.

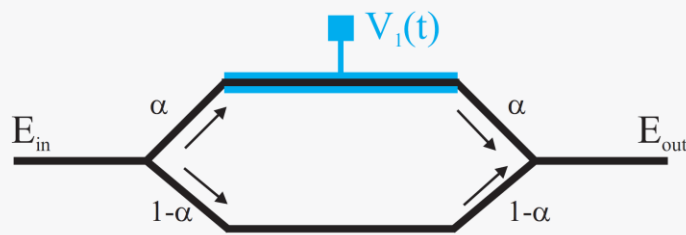


# Optical Modulators in Photonic Integrated Circuits

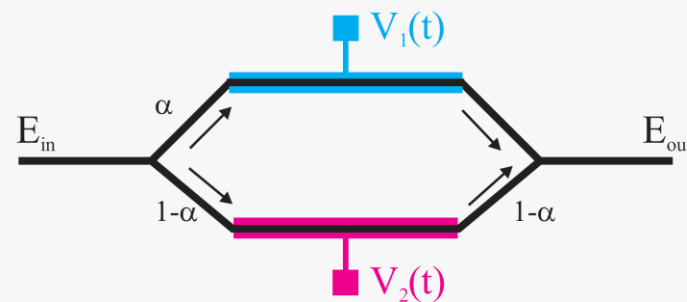
## Optical Phase Shifters and Modulators

- Phase shifter introduces additional phase shift in guided-light.
- Additional phase shift:  $\Delta\phi = (2\pi L\Delta n) / \lambda$
- $\Delta n$ : Electro-optic effect (via free carrier plasma dispersion effect) or thermo-optic effect.
- Most common structure: PN/PIN diode or MOS Capacitor in a rib waveguide.

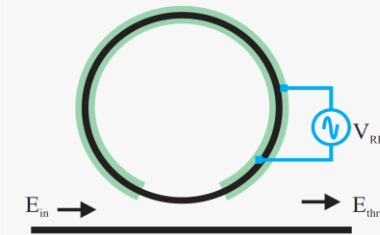
## Different Modulator Structures



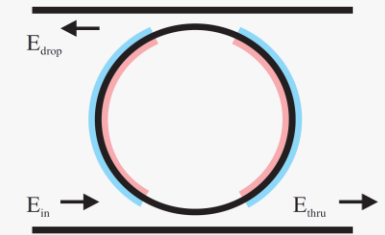
Single MZM



Push-Pull MZM



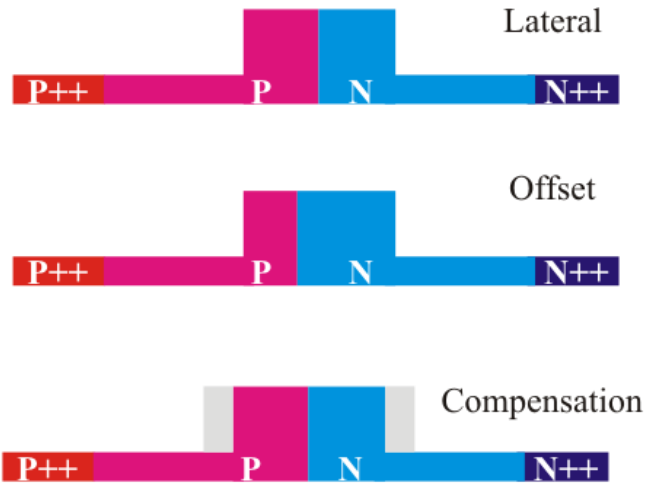
All-Pass MRM



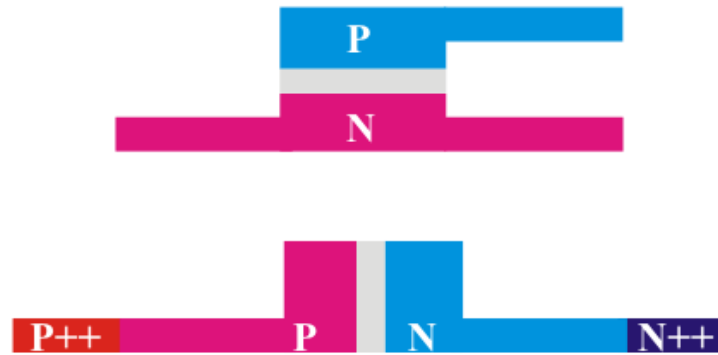
Add-Drop MRM

# Different Optical Modulator Structures

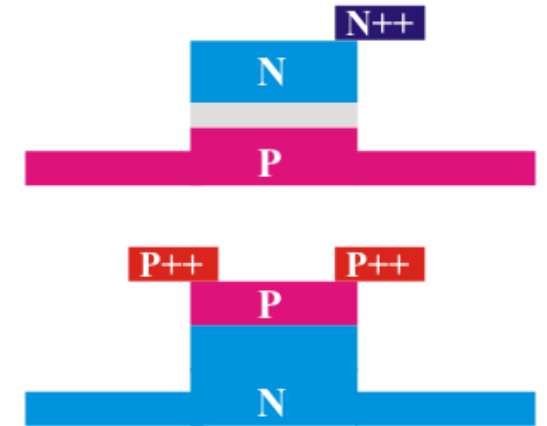
**PN Junction**



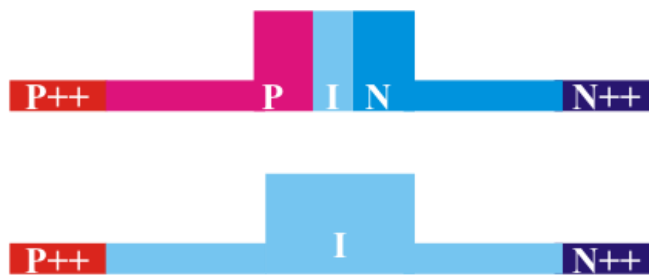
**MOS Junction**



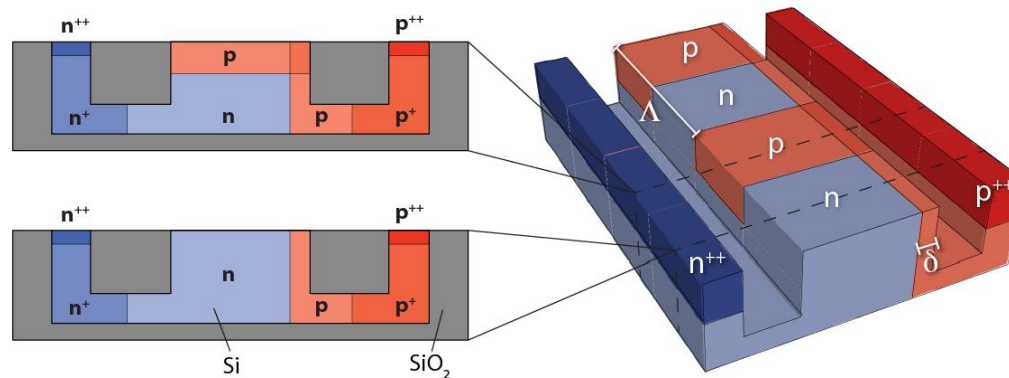
**Vertical PN Junction**



**PIN Junction**

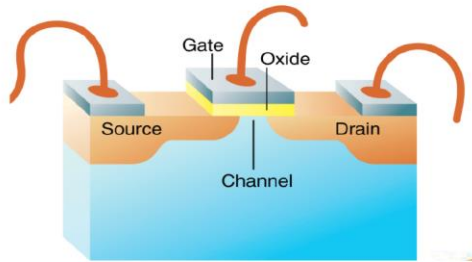


**Interleaved PN Junction**

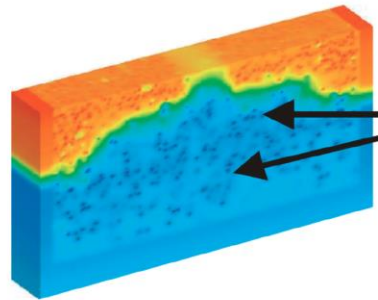


Source: Opt. Express **20**, 26411-26423 (2012)

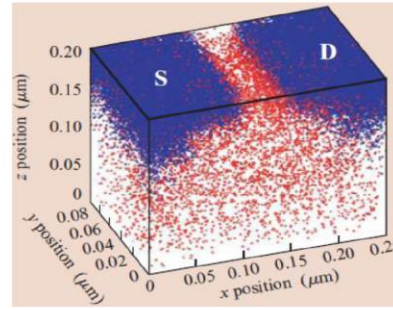
# Random Dopant Fluctuations



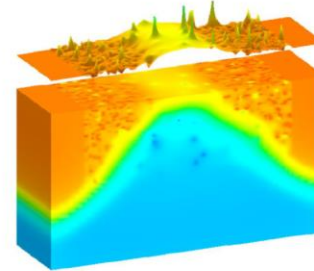
30 nm x 30 nm  
Field Effect Transistor



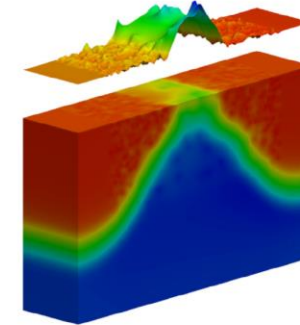
RDF induced  
potential fluctuations



Dopant distribution in a  
32 nm MOSFET



RDF induced  
potential fluctuations



RDF induced local rise  
of channel acceptors in a  
typical 25 nm MOSFET

Source: Roy et al., Science Magazine, vol. 309, pp.388-389, July 2005.

Source: Gabriele Tocci, Masters Thesis, KTH, 2010.

Source: L. Gerrer et al., Microelectronics Reliability, vol. 52, pp. 1918-1923, 2012.

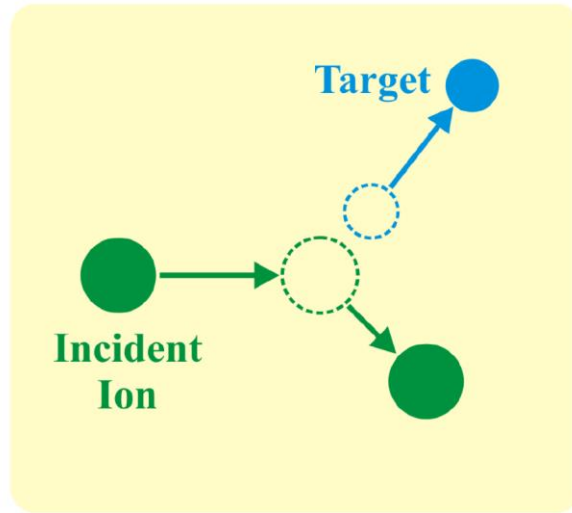
Insertion loss in MZM as a function of doping<sup>1</sup>:

$$IL = 2\alpha_{sp} + \left( A \cdot \sqrt{N_{dop}} + \frac{\alpha_{wg}}{\sqrt{N_{dop}}} \right) \cdot B$$

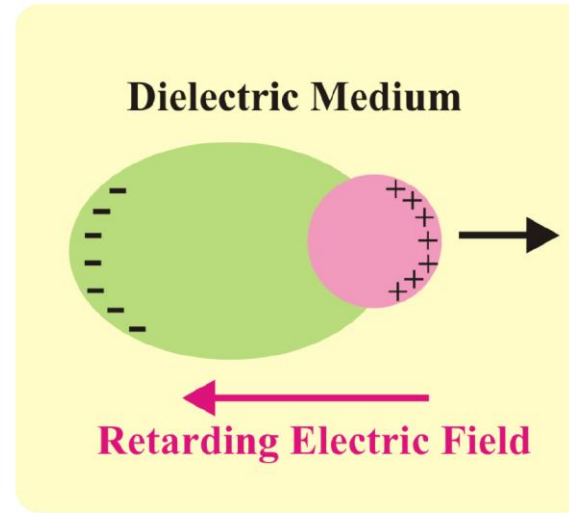
where  $\alpha_{sp}$ : splitter loss;  $A, B$ : two coefficients related to length and light overlap factor;  $N_{dop}$ : doping concentration; and  $\alpha_{wg}$ : optical propagation loss.

<sup>1</sup> Xi Xiao et.al., *Optics Express*, vol. 21, no. 4, pp. 4416-4125, 2013.

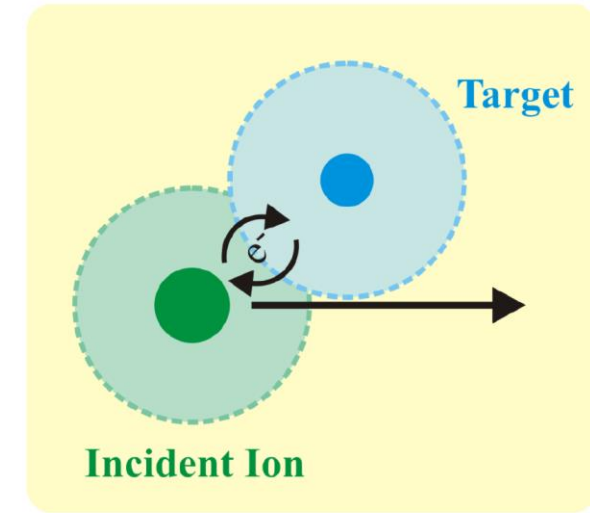
# Origin of Random Dopant Fluctuations



(a) Nuclear stopping



(b) Non-local electronic stopping



(c) Local electronic stopping

**Plausible Solution?**

**Use of Electrostatic Doping (ED)**



# Concept of Electrostatic Doping (ED)

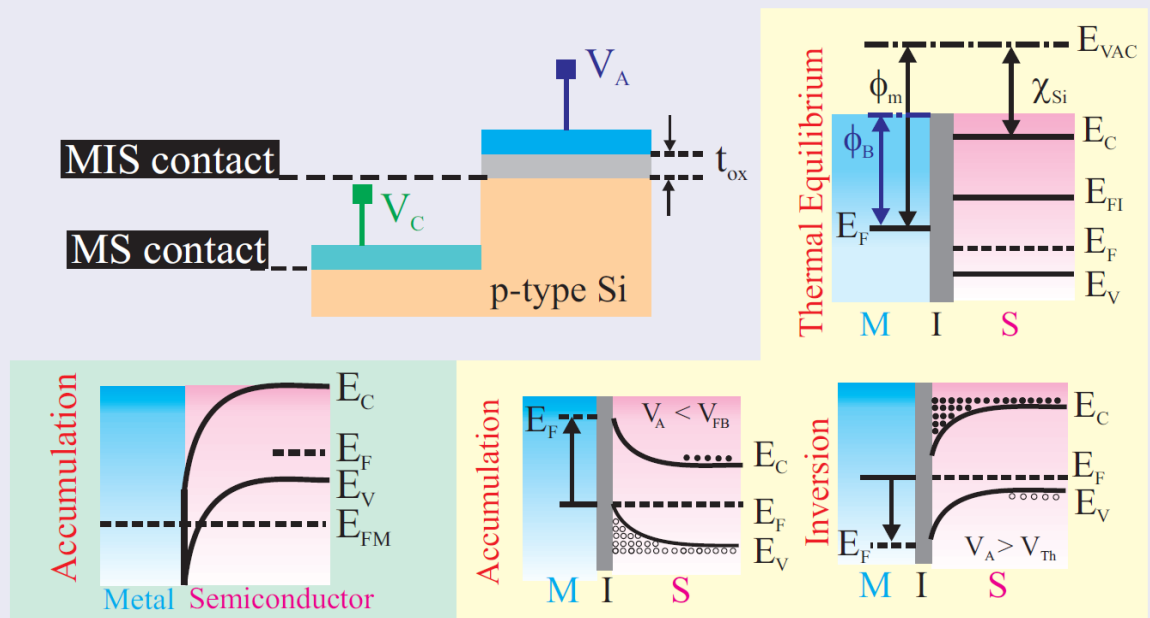


Figure: Concept of ED in metal-semiconductor and metal-insulator-semiconductor junction.

## Types of ED in Semiconductor Devices

- **Schottky Barrier Based Doping**  
SB-MOSFET, SB-FinFET, CNT
- **Work-function Induced Doping**  
CP-PN/PIN diode, CP-BJT, CP-TFET
- **Bias Induced Doping**  
Lateral/ vertical PN junction, DG-TFET

## Plausible ED in Si-Ph Devices

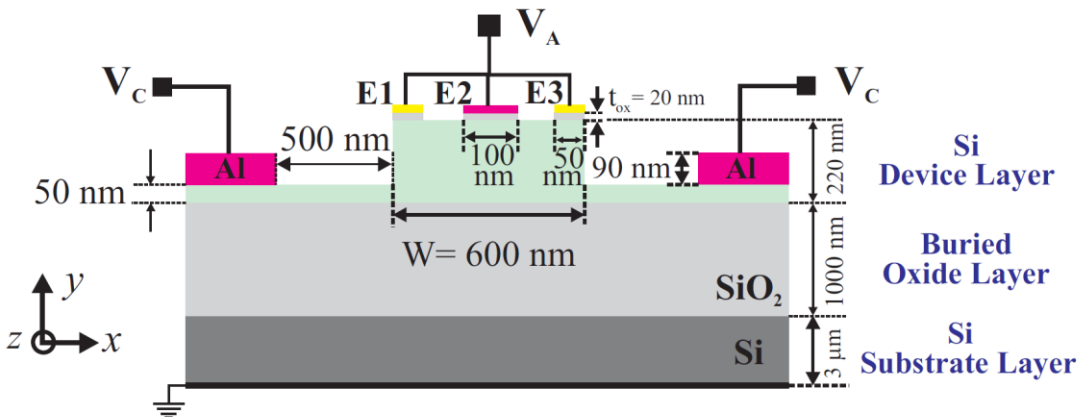
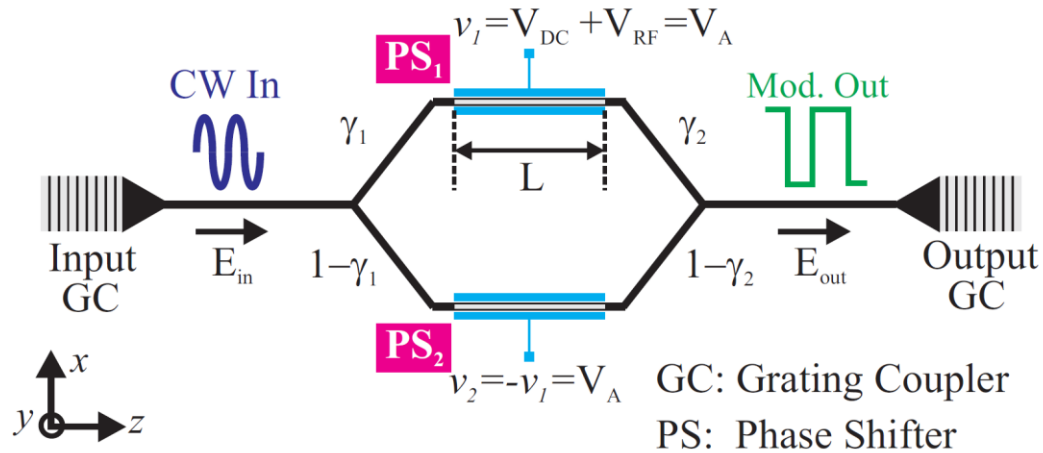
- **Work-function induced doping**  
Utilizes different metal as electrodes.
- **Bias induced doping**  
Use of proper bias voltages.

## Design Objectives

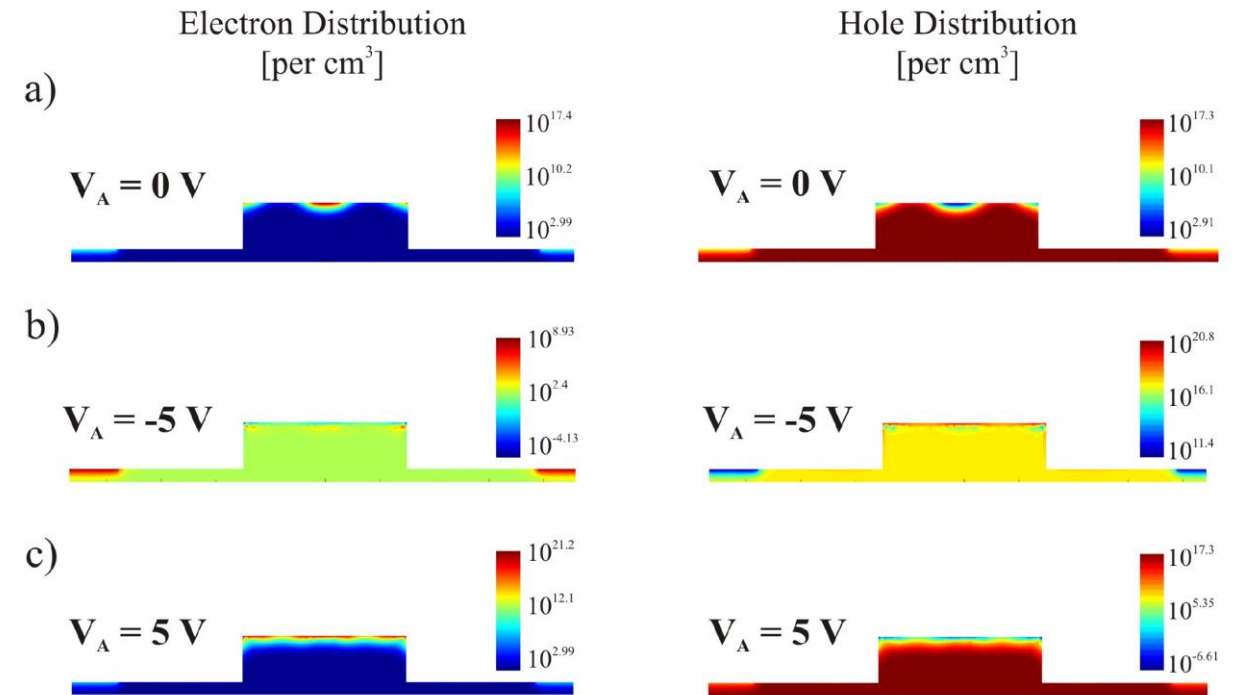
- ED assisted optical phase shifter based Push-Pull Mach-Zehnder Modulator (MZM).

# Proposed ED Assisted Push-Pull MZM

## Proposed Modulator Structure



## Carrier Distribution Across ED Assisted Optical Phase Shifter



# Mathematical Model of Proposed Modulator

Referring to the device structure, the output electric field of the modulated signal ( $E_{out}$ ) can be expressed as:

$$E_{out} = \left[ \sqrt{\gamma_1 \gamma_2} e^{-j\Delta\phi(v_1)} e^{-\Delta\alpha(v_1)L} \right] e^{-(j\phi_0 + \alpha_0 L)} E_{in} + \left[ \sqrt{(1-\gamma_1)(1-\gamma_2)} e^{-j\Delta\phi(v_2)} e^{-\Delta\alpha(v_2)L} \right] e^{-(j\phi_0 + \alpha_0 L)} E_{in}$$

For symmetric power splitting and combining i.e.  $\gamma_1 = \gamma_2 = 1/2$ , the above equation reforms to:

$$E_{out} = \frac{E_{in}}{2} \left[ e^{-j\Delta\phi(v_1)} e^{-\Delta\alpha(v_1)L} + e^{-j\Delta\phi(v_2)} e^{-\Delta\alpha(v_2)L} \right] e^{-(j\phi_0 + \alpha_0 L)}$$

where,  $\Delta\phi(v) = \frac{2\pi L}{\lambda} \Delta n(v)$  : bias voltage induced phase change in the optical phase shifter

$\lambda$  = operating wavelength;

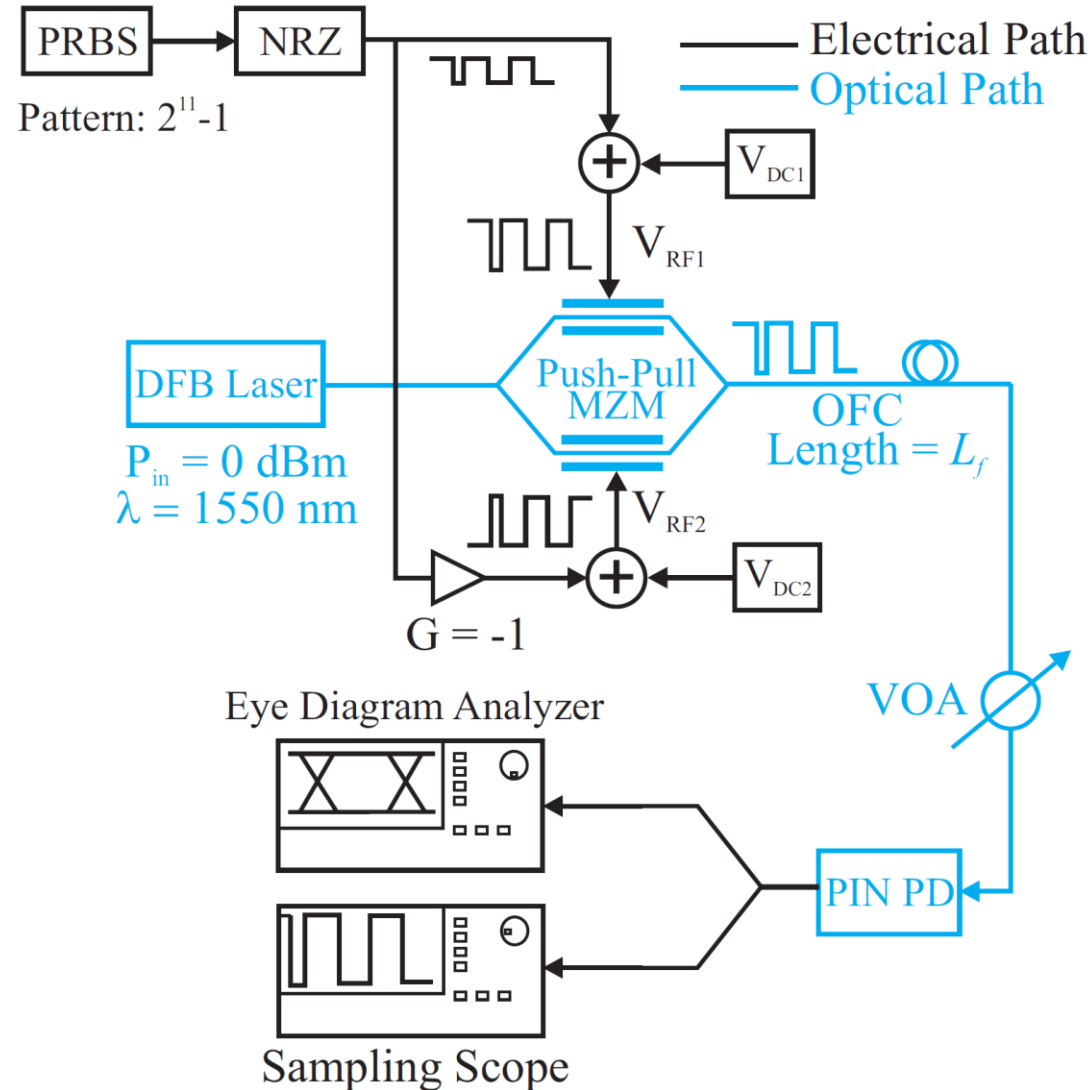
$\phi_0$  = phase shift at zero bias voltage;

$\alpha_0$  = loss coefficient at zero bias voltage;

$L$  = length of the phase shifter.



# Simulation Setup for the Proposed Modulator



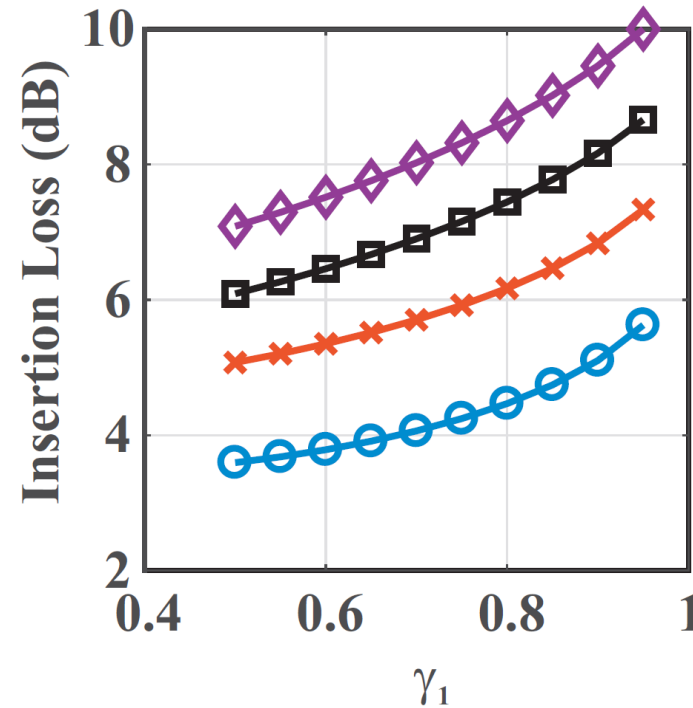
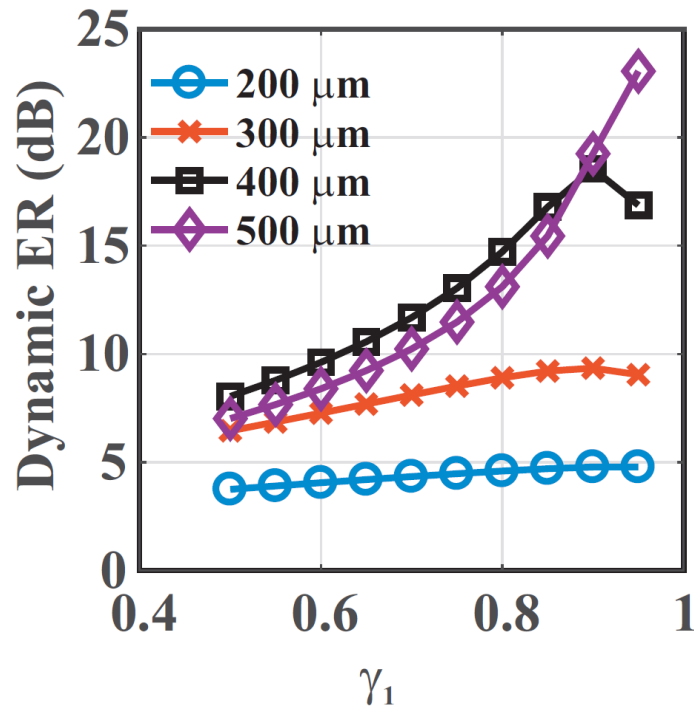
## Used Simulation Platform

Carrier Dynamics: Lumerical Device CT

Modal Calculation: Lumerical Mode Solutions

Transmission System: Lumerical Interconnect

# Simulation Results: Dynamic Performance Metrics



## Performance Metrics: Design 1

$L = 200 \mu\text{m}$

3-dB EO Bandwidth: 28 GHz

Maximum operating frequency: 35.2 GHz

## Performance Metrics: Design 2

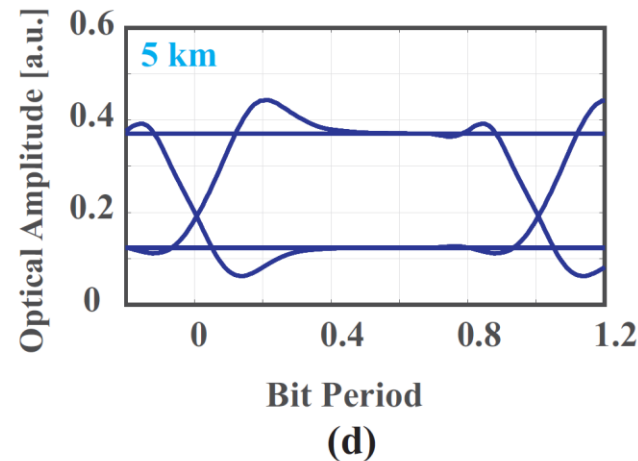
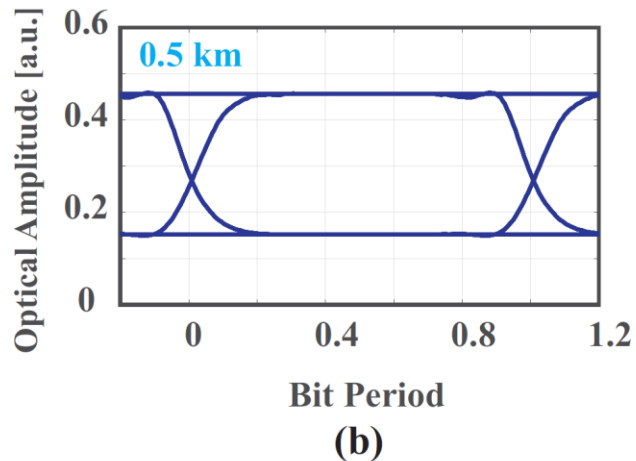
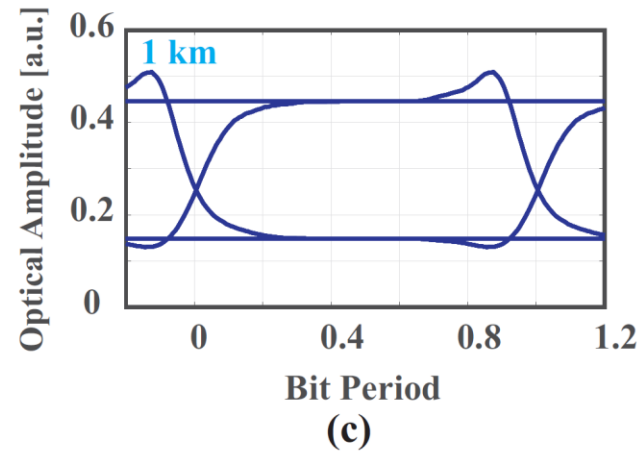
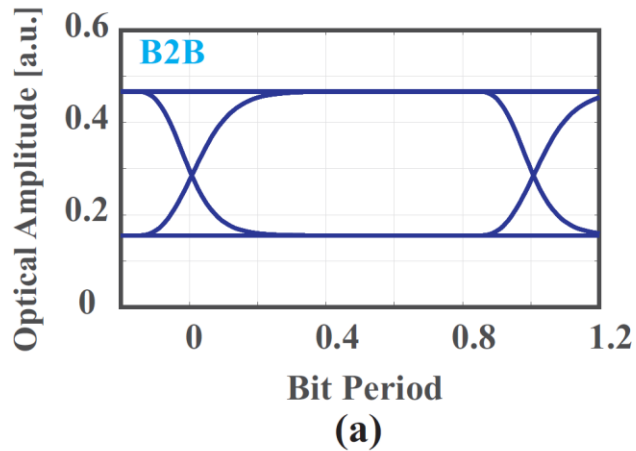
$L = 400 \mu\text{m}$

3-dB EO Bandwidth: 22.7 GHz

Maximum operating frequency: 30.3 GHz



# Simulation Results: Eye Diagram After Different Fiber Length at 10 Gb/s Data Rate



| Fiber Length (km) | Dynamic ER (dB) |
|-------------------|-----------------|
| B2B               | 5.93            |
| 0.5               | 5.26            |
| 1.0               | 4.68            |
| 5.0               | 3.64            |

## Transient Performance Metrics

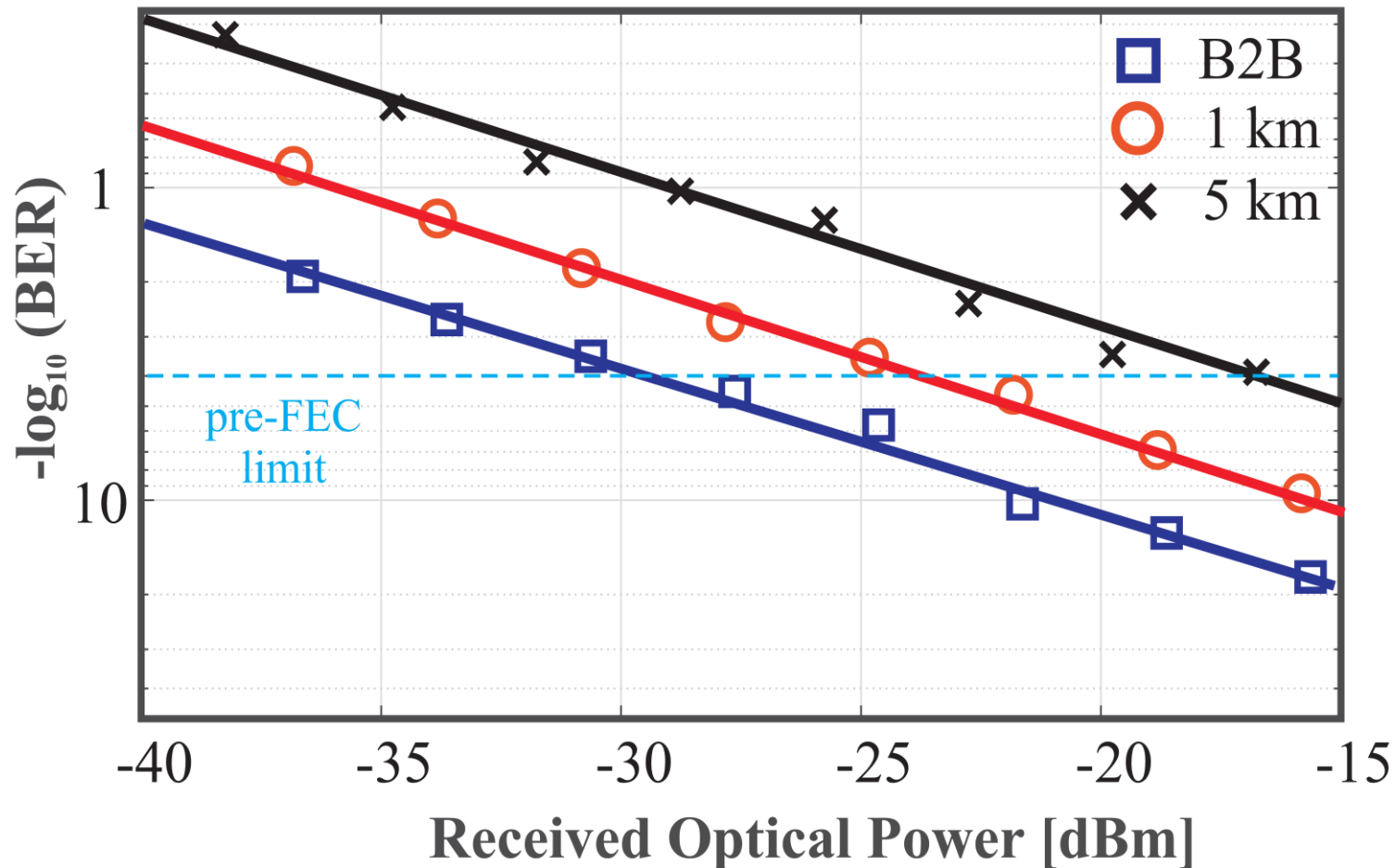
$L = 200 \mu\text{m}$

3-dB EO Bandwidth: 28 GHz

Maximum operating frequency: 35.2 GHz



# Simulation Results: BER Performance



## Simulation Parameters

Data Rate: 25 Gb/s

Input Data:  $2^{11}-1$ , PRBS

Thermal Noise: -410 dBm/Hz

Dark Current: 5 nA

Responsivity: 0.85 A/W



# Comparative Performance Study

| Reference | Year | Material              | L<br>[mm] | ER<br>[dB] | IL<br>[dB] | $f_{max}$<br>[GHz] | $V_{\pi}L_{\pi}$<br>[V.cm] |
|-----------|------|-----------------------|-----------|------------|------------|--------------------|----------------------------|
| [10]      | 2019 | Si                    | 3         | 3.6        | 9.1        | 32                 | 0.55                       |
| [11]      | 2019 | Si–LiNbO <sub>3</sub> | 3         | 5.0        | 2.5        | 112                | 2.20                       |
| [19]      | 2019 | AlGaAs                | 10        | 3.0        | 7.5        | -                  | 1.00                       |
| This work | 2020 | Si                    | 0.2       | 4.7        | 5.1        | 30.3               | 0.36-0.74                  |

[10] G. Zhou, L. Zhou, Y. Guo, L. Liu, L. Lu, and J. Chen, “High Efficiency Silicon Mach-Zehnder Modulator With U-shaped PN Junctions,” in CLEO: Applications and Technology. Optical Society of America, 2019, pp. JTh2A–42.

[11] M. He, M. Xu, Y. Ren, J. Jian, Z. Ruan, Y. Xu, S. Gao, S. Sun, X. Wen, L. Zhou et al., “High-performance Hybrid Silicon And Lithium Niobate Mach–Zehnder Modulators For 100 Gbit.s<sup>-1</sup> and Beyond,” Nature Photonics, vol. 13, no. 5, pp. 359–364, 2019.

[19] P. Bhasker, J. Norman, J. E. Bowers, and N. Dagli, “Low Voltage, High Optical Power Handling Capable, Bulk Compound Semiconductor Electro-Optic Modulators at 1550 nm,” Journal of Lightwave Technology, vol. 33, no. 8, pp. 2308-2314, 2020.





# Conclusions

- Push-Pull Mach-Zehnder intensity modulator with electrostatic doping assisted optical phase shifter for photonic integrated circuits is plausible.
- For 200  $\mu\text{m}$  long proposed MZM, estimated dynamic ER is 4.7 dB with 5.1 dB of IL at 10 Gb/s data rate.
- 3-dB electro-optic bandwidth of MZM with  $L = 200 \mu\text{m}$ : 28 GHz.
- Maximum operating frequency of MZM with  $L = 200 \mu\text{m}$ : 35.2 GHz.
- Transmission over 5 km SSMF fiber also plausible.
- Power penalty at 25 Gb/s data rate over 1 km and 5 km SSMF: 5 dB and 13 dB, respectively.



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9. S. Pal, P. K. Tiwari, and S. Gupta, “A Proposal For An Electrostatic Doping-assisted Electro-absorption Modulator For Intrachip Communication,” *IEEE Transactions on Electron Devices*, vol. 66, no. 5, pp. 2269–2275, May 2019.
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11. M. He, M. Xu, Y. Ren, J. Jian, Z. Ruan, Y. Xu, S. Gao, S. Sun, X. Wen, L. Zhou et al., “High-performance Hybrid Silicon And Lithium Niobate Mach–Zehnder Modulators For 100 Gbit.s<sup>-1</sup> and Beyond,” *Nature Photonics*, vol. 13, no. 5, pp. 359–364, 2019.
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**Thank You**